

APPLICATIONS BULLETIN

How Can I Further Improve my Print Process?

Run the Double Play:

nanoclear
+ Engineered Solvent Under Wipe
= Best-In-Class Print Process

NanoClear Coated Stencil



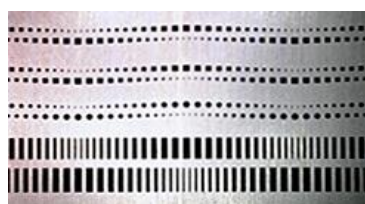
Dry Wipe

- Clear apertures
- Trace smears of flux on stencil surface



IPA Wipe

- Clogged Apertures
- Smears of flux on stencil surface



Engineered Solvent Wipe

- Clear Apertures
- No flux on stencil surface

The photos above show a popular lead-free solder paste with a stencil coated with NanoClear. The flux was tinted with UV tracer to improve its visibility.

How to check a solder paste's compatibility with under wipe solvent

Often times, aperture blockages are caused by incompatibility with under wipe solvents. Solvents containing IPA or other alcohols can react with the solder paste and cause it to congeal.

Extrude solder paste into glass beakers or sample jars containing the solvent



Lead-free solder paste fluxes use complex chemistries that may not be fully soluble in IPA

Paste solubility image courtesy of Kyzen Corporation

[Download](#) the published study

See Also [Why Should Softer Under Wipes Be Used with Nanocoating?](#)

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